



Designation: F 542 – 9802

An American National Standard

Standard Test Method for Exothermic Temperature of Encapsulating Compounds for Electronic and Microelectronic Encapsulation¹

This standard is issued under the fixed designation F 542; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ε) indicates an editorial change since the last revision or reapproval.

1. Scope

1.1 This test method provides results that are related to the maximum temperature reached in a specific volume by a reacting liquid encapsulating compound, and the time from initial mixing to the time when this peak exothermic temperature is reached.

1.2 This test method provides a means to measure the peak exothermic temperature of an encapsulating compound.

1.3 *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.* For specific hazard statements see Section 8.

NOTE 1—There is no equivalent IEC standard.

2. Referenced Documents

2.1 *ASTM Standards:*

D 1711 Terminology Relating to Electrical Insulation²

¹ This test method is under the jurisdiction of ASTM Committee D-9 D09 on Electrical and Electronic Insulating Materials, and is the direct responsibility of Subcommittee D 09.01 on Electrical Insulating Varnishes, Powders; and Encapsulating Compounds.

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